

Product Summary

V _{DS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
-8V	5.7mΩ@V _{GS} = -4.5V	-13.2A

Description

This 3rd generation Lateral MOSFET (LD-MOS) is engineered to minimize on-state losses and switch ultra-fast, making it ideal for high efficiency power transfer. It uses Chip-Scale Package (CSP) to increase power density by combining low thermal impedance with minimal R_{DS(ON)} per footprint area.

Applications

- DC-DC Converters
- Battery Management
- Load Switch

Features

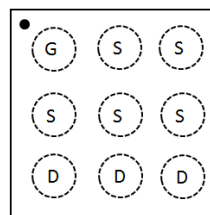
- LD-MOS Technology with the Lowest Figure of Merit:
- R_{DS(ON)} = 5.7mΩ to Minimize On-State Losses
- Q_g = 8.2nC for Ultra-Fast Switching
- V_{GS(TH)} = -0.6V Typ. for a Low Turn-On Potential
- CSP with Footprint 1.5mm × 1.5mm
- Height = 0.60mm for Low Profile
- ESD Protection of Gate
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact_us@diodes.com) or your local Diodes representative.**
<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

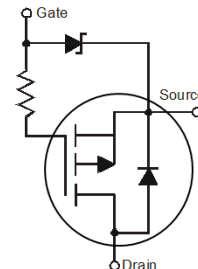
- Case: U-WLB1515-9
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal: Finish - SnAgCu. Solderable per MIL-STD-202 Method 208 @1
- UBM Size: 245μm
- Terminal Connections: See Diagram Below
- Weight: 0.0018 grams (Approximate)



U-WLB1515-9 (Type F)



Top-View
Pin Configuration



Equivalent Circuit

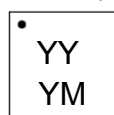
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1008UCB9-7	U-WLB1515-9 (Type F)	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

U-WLB1515-9 (Type F)



YY = Product Type Marking Code
YM = Date Code Marking
Y or $\bar{Y}$ = Year (ex: G = 2019)
M or $\bar{M}$ = Month (ex: 9 = September)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	G	H	I	J	K	L	M	N	O	P	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-8	V
Gate-Source Voltage			V _{GSS}	-6	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _A = +25°C	I _D	-9.8	A
		T _A = +70°C		-7.8	
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _A = +25°C	I _D	-13.2	A
		T _A = +70°C		-10.5	
Pulsed Drain Current (Pulse Duration 10μs, Duty Cycle ≤1%)			I _{DM}	-80	A
Continuous Source Pin Current (Note 6)			I _S	-1.8	A
Pulsed Source Pin Current (Pulse Duration 10μs, Duty Cycle ≤1%)			I _{SM}	-80	A
Continuous Gate Current			I _G	-0.8	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	0.84	W
Total Power Dissipation (Note 6)	P _D	1.53	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	151.4	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	82	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-8	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	—	—	-1	μA	V _{DS} = -6.4V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	-100	nA	V _{GS} = -6.0V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	-0.6	-1.1	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	4.7	5.7	mΩ	V _{GS} = -4.5V, I _D = -2A
			6.3	8.2		V _{GS} = -3.0V, I _D = -2A
			6.8	9.1		V _{GS} = -2.5V, I _D = -2A
Diode Forward Voltage (Note 6)	V _{SD}	—	-0.63	-1	V	V _{GS} = 0V, I _S = -2A
Reverse Recovery Charge	Q _{RR}	—	9.2	—	nC	V _{DD} = -5V, I _F = -2A, di/dt = 200A/μs
Reverse Recovery Time	t _{RR}	—	25	—	ns	
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	900	—	pF	V _{DS} = -4V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	730	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	158	—	pF	
Series Gate Resistance	R _G	—	21.4	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge	Q _g	—	8.2	—	nC	V _{GS} = -4.5V, V _{DS} = -4V, I _D = -2A
Gate-Source Charge	Q _{gs}	—	0.9	—	nC	
Gate-Drain Charge	Q _{gd}	—	1.0	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	20.0	—	ns	V _{DD} = -4V, V _{GS} = -4.5V, I _D = -2A, R _G = 10Ω
Turn-On Rise Time	t _r	—	5.8	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	99.6	—	ns	
Turn-Off Fall Time	t _f	—	36.4	—	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout.
 - Device mounted on FR-4 material with 1-inch² (6.45cm²), 2oz (0.071mm thick) Cu.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

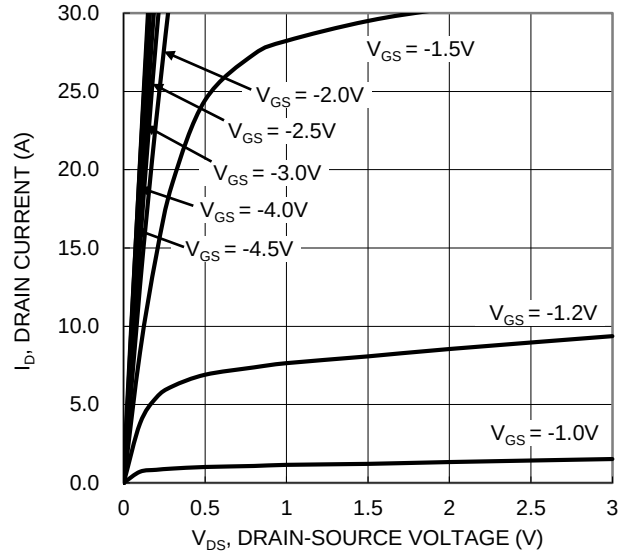


Figure 1. Typical Output Characteristic

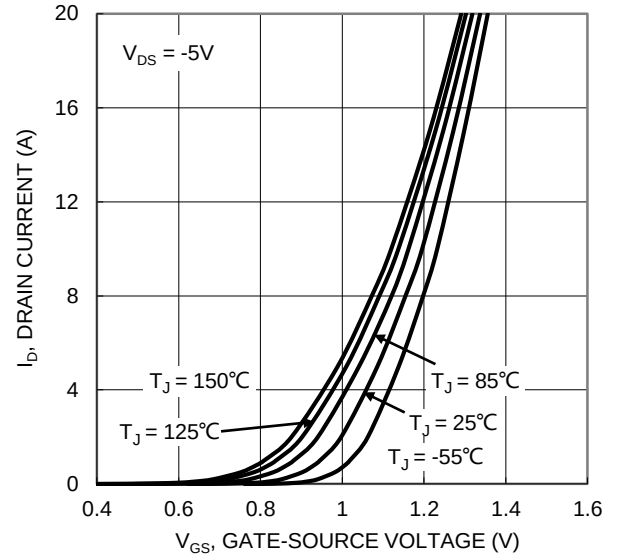


Figure 2. Typical Transfer Characteristic

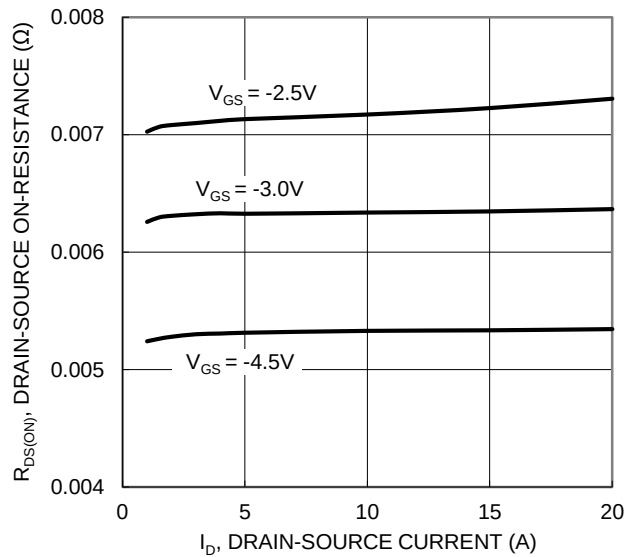


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

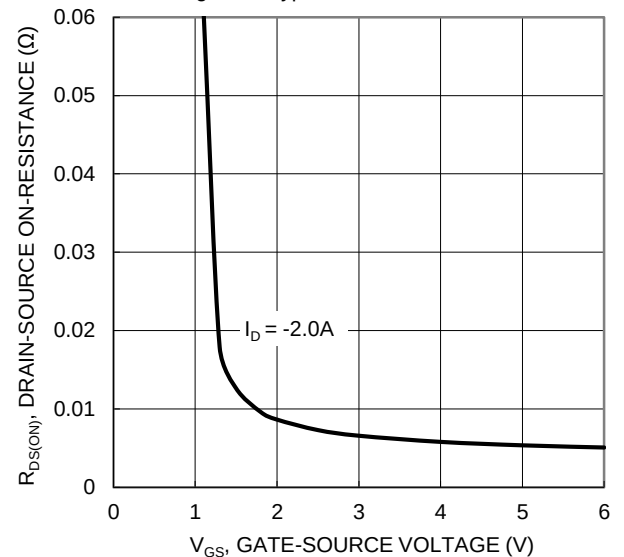


Figure 4. Typical Transfer Characteristic

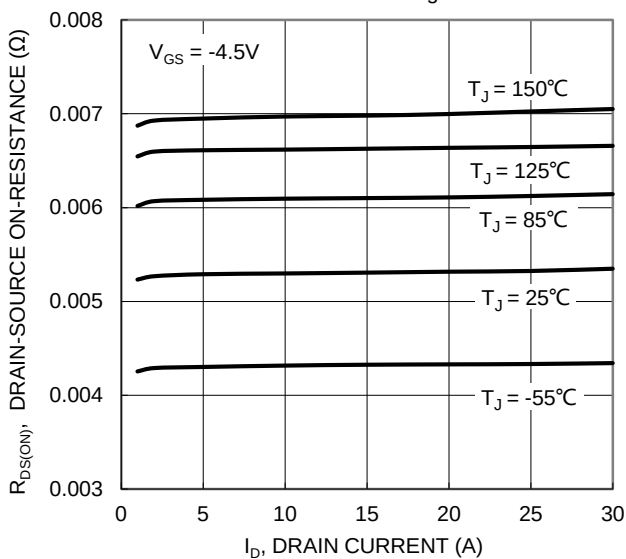


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

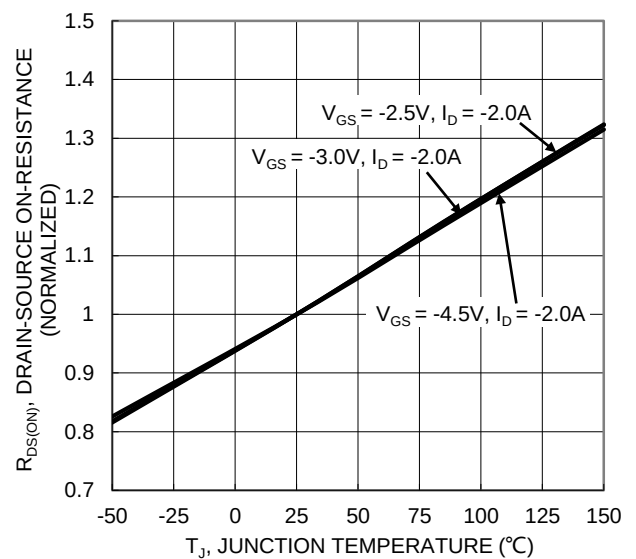
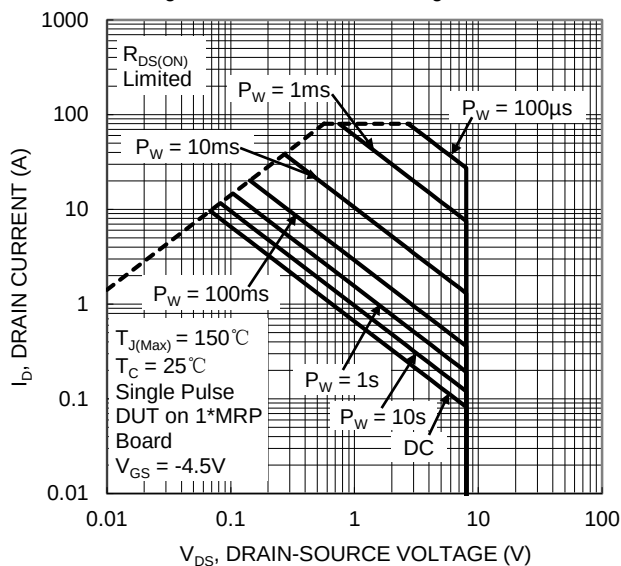
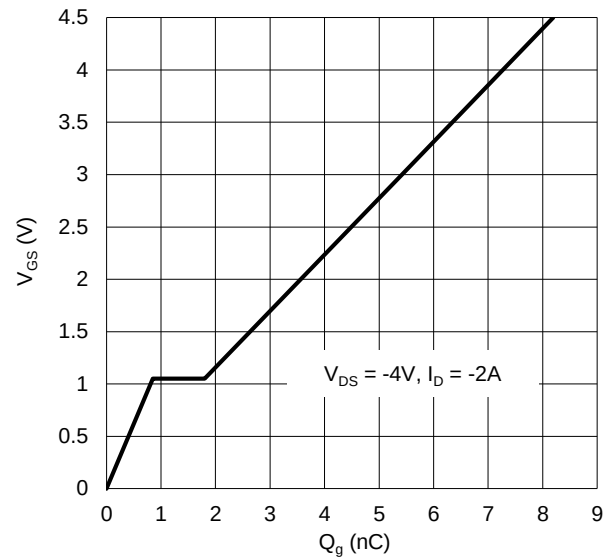
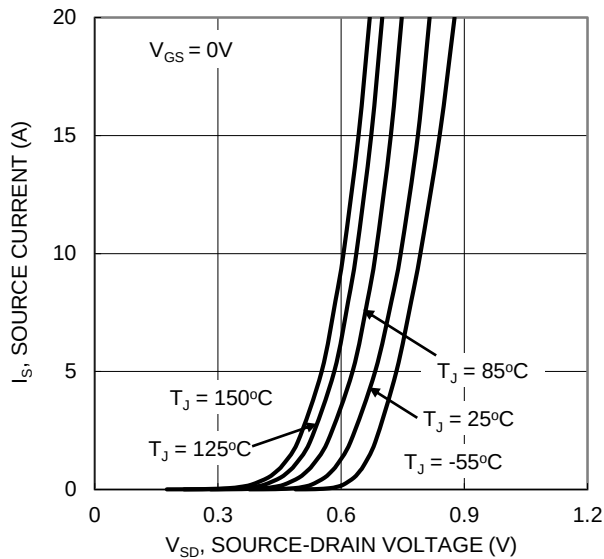
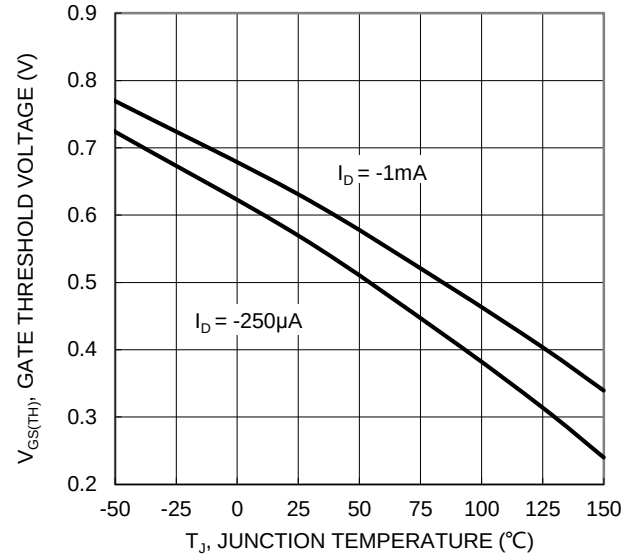
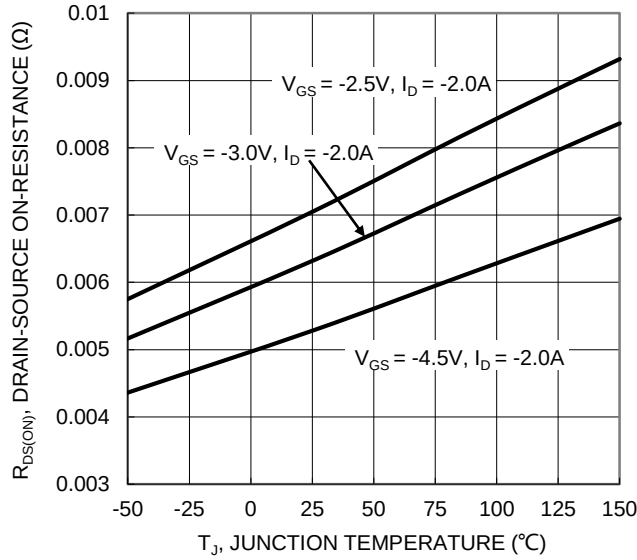


Figure 6. On-Resistance Variation with Junction Temperature



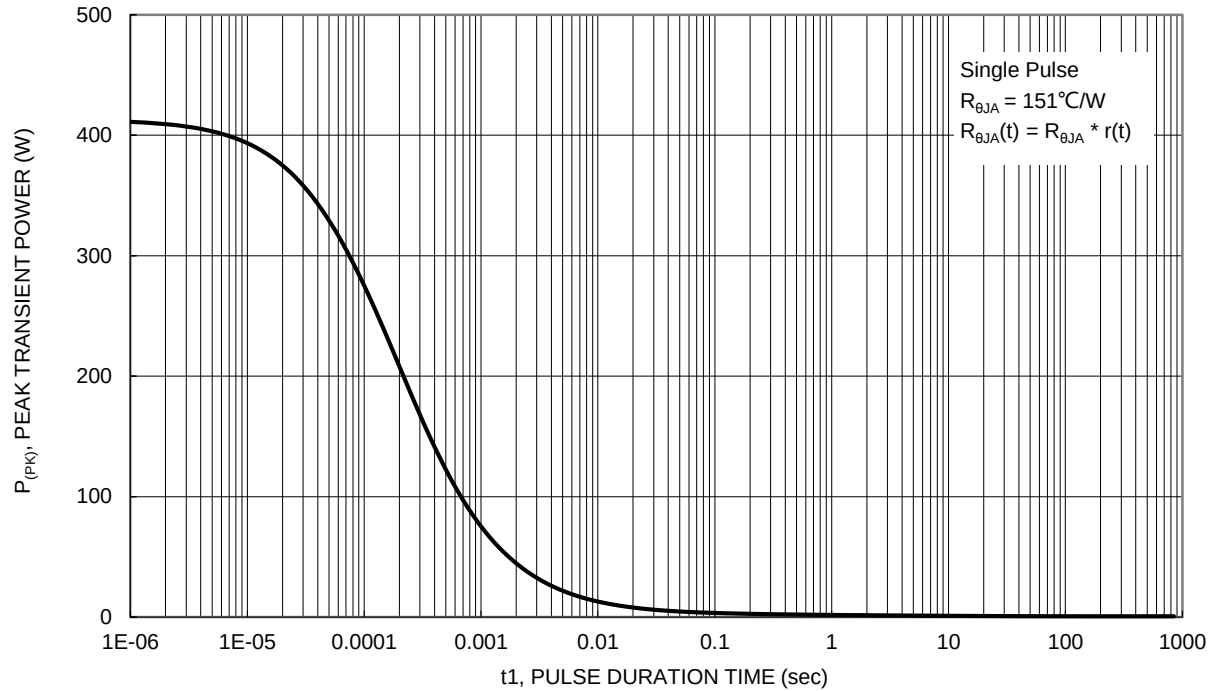


Figure 12. Single Pulse Maximum Power Dissipation

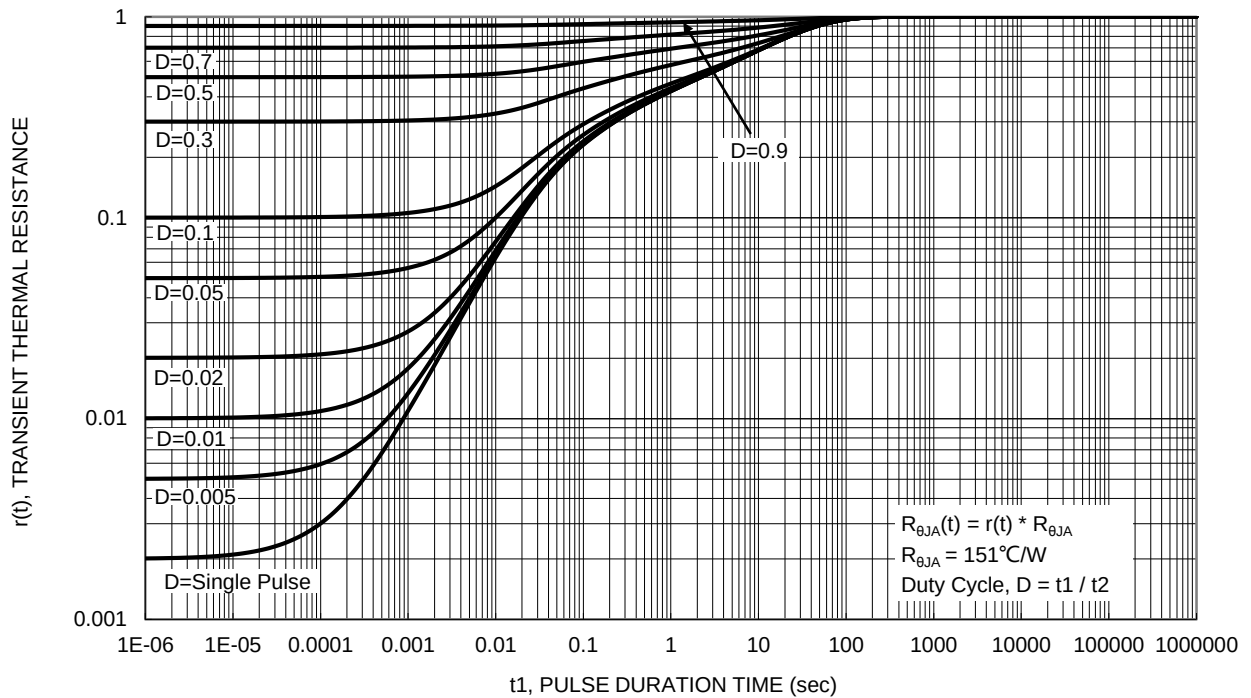
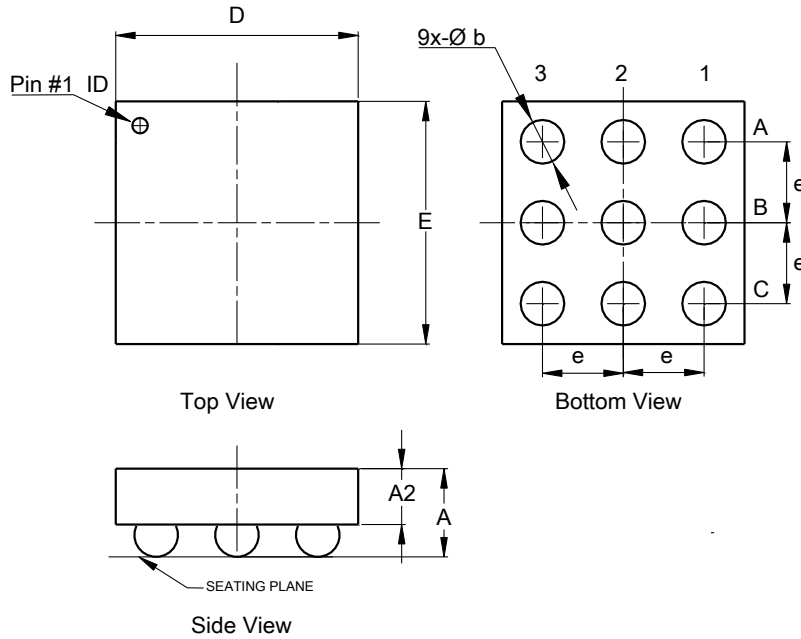


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-WLB1515-9 (Type F)

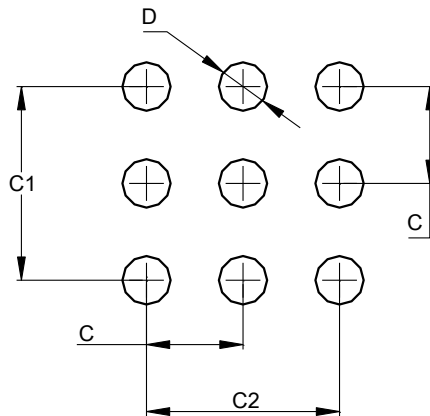


U-WLB1515-9 (Type F)			
Dim	Min	Max	Typ
A	--	0.60	--
A2	0.31	0.36	0.335
b	0.220	0.320	0.270
D	1.48	1.53	1.505
E	1.48	1.53	1.505
e	--	--	0.50
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-WLB1515-9 (Type F)



Dimensions	Value (in mm)
C	0.50
C1	1.00
C2	1.00
D	0.25

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